



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2823
#20/E
12-27-2
Robertson
Amendt

In re the Application of:

Heinen, et al.

Docket No.: TI-23158

Serial No.: 09/186,973

Examiner: Foong, S.

Filed: 11/05/98

Art Unit: 2823

For: Wafer-scale Assembly of Chip-size Packages

Amendment under 37 CFR 1.111

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with
the U.S. Postal Service as First Class Mail in an envelope addressed
to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

11-14-02

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 08/14/02. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

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TECHNICAL SERVICES DIVISION